

WHAT IS CLAIMED IS:

1. An apparatus comprising:

a plurality of pliant conductive elements, a first end of one of the plurality of pliant  
conductive elements to be electrically coupled to a first electrical contact of an integrated  
5 circuit substrate and a second end of the one of the plurality of pliant conductive elements to  
be electrically coupled to a second electrical contact of an integrated circuit die.

2. An apparatus according to Claim 1, further comprising:

a pliant material in which the plurality of pliant conductive elements are disposed.

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3. An apparatus according to Claim 2, wherein the pliant material comprises a pliant  
dielectric material.

4. An apparatus according to Claim 1, further comprising:

15 the integrated circuit substrate comprising the first electrical contact.

5. An apparatus according to Claim 4, wherein the integrated circuit substrate  
comprises an integrated circuit package.

20 6. An apparatus according to Claim 4, wherein the integrated circuit substrate  
comprises a motherboard.

7. An apparatus according to Claim 1, further comprising:

the integrated circuit die comprising the second electrical contact.

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8. An apparatus according to Claim 1, wherein a first end of a second one of the plurality of pliant conductive elements is to be electrically coupled to a third electrical contact of the integrated circuit substrate and a second end of the second one of the plurality of pliant conductive elements is to be electrically coupled to a fourth electrical contact of the integrated circuit die.

9. A method comprising:  
forming an integral conductive element, the integral conductive element defining a plurality of recesses;  
10 depositing a first pliant material in the plurality of recesses to form a first structure;  
removing portions of the integral conductive element to form a plurality of pliant conductive elements; and  
depositing a second pliant material around the plurality of pliant conductive elements to form a second structure.

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10. A method according to Claim 9, further comprising:  
placing the first structure on a carrier after depositing the first pliant material; and  
removing the second structure from the carrier after depositing the second pliant material.

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11. A method according to Claim 10, wherein placing the first structure on a carrier comprises:  
placing the first structure on a release layer disposed on a carrier, and  
wherein removing the second structure from the carrier comprises:  
25 releasing the second structure from the release layer.

12. A method according to Claim 10, further comprising:

bonding a first end of one of the plurality of pliant conductive elements to a first electrical contact of an integrated circuit substrate and a second end of the one of the plurality of pliant conductive elements to a second electrical contact of an integrated circuit die.

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13. A method according to Claim 10, wherein depositing the second pliant material comprises:

depositing a second pliant material around the plurality of pliant conductive elements to form the second structure having a first side and a second side,

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wherein the first side includes the first pliant material, the second pliant material and a plurality of first ends of a respective plurality of pliant conductive elements, and

wherein the second side includes the second pliant material and a plurality of second ends of the respective plurality of pliant conductive elements.

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14. A method comprising:

depositing a plurality of elements on a carrier, the plurality of elements comprising first pliant material;

depositing an integral conductive element on the plurality of elements;

removing portions of the integral conductive element to form a plurality of pliant conductive elements; and

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depositing a second pliant material around the plurality of pliant conductive elements to form a first structure.

15. A method according to Claim 14, further comprising:

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removing the first structure from the carrier after depositing the second pliant material.

16. A method according to Claim 15, wherein depositing the plurality of elements on the carrier comprises:

depositing the plurality of elements on a release layer disposed on the carrier, and

5 wherein removing the first structure from the carrier comprises:

releasing the first structure from the release layer.

17. A method according to Claim 14, further comprising:

10 bonding a first end of one of the plurality of pliant conductive elements to a first electrical contact of an integrated circuit substrate and a second end of the one of the plurality of pliant conductive elements to a second electrical contact of an integrated circuit die.

18. A method according to Claim 14, wherein depositing the second pliant material  
15 comprises:

depositing a second pliant material around the plurality of pliant conductive elements to form the second structure having a first side and a second side,

wherein the first side includes the first pliant material, the second pliant material and a plurality of first ends of a respective plurality of pliant conductive elements, and

20 wherein the second side includes the second pliant material and a plurality of second ends of the respective plurality of pliant conductive elements.

19. A device comprising:

an integrated circuit die comprising a first plurality of electrical contacts;

25 an integrated circuit substrate comprising a second plurality of electrical contacts;

and

an interconnect patch comprising a plurality of pliant conductive elements, a first end of one of the plurality of pliant conductive elements coupled to one of the first plurality of electrical contacts and a second end of the one of the plurality of pliant conductive elements coupled to one of the second plurality of electrical contacts.

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20. A device according to Claim 19, wherein a first end of a second one of the plurality of pliant conductive elements is coupled to a second one of the first plurality of electrical contacts and a second end of the second one of the plurality of pliant conductive elements is coupled to the second one of the second plurality of electrical contacts.

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21. A system comprising:

a microprocessor comprising:

an integrated circuit die comprising a first plurality of electrical contacts;

an integrated circuit substrate comprising a second plurality of electrical  
contacts; and

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an interconnect patch comprising a plurality of pliant conductive elements, a first end of one of the plurality of pliant conductive elements coupled to one of the first plurality of electrical contacts and a second end of the one of the plurality of pliant conductive elements coupled to one of the second plurality of electrical  
contacts; and

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a double data rate memory electrically coupled to the microprocessor.

22. A system according to Claim 21, wherein a first end of a second one of the plurality of pliant conductive elements is coupled to a second one of the first plurality of electrical contacts and a second end of the second one of the plurality of pliant conductive elements is coupled to the second one of the second plurality of electrical contacts.

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